



100% Material Declaration Data Sheet HQ208

PK162 (v1.2) October 3, 2006

Material Declaration Data Sheet

Average Weight: 10.943 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					0.16981	1.55%
	Silicon	7440-21-3	100.00		0.169814	
Die Attach Material					0.01531	0.14%
	Resin	Trade Secret	25.00		0.003828	
	Silver	7440-22-4	75.00		0.011483	
Mold Compound					3.24216	29.63%
	Epoxy Resin (EP)	Trade Secret	16.00		0.518746	
	Silica	60676-86-0	84.00		2.723414	
Leadframe					0.37676	3.44%
	Copper	7440-50-8	99.25		0.373939	
	Chromium	7440-47-3	0.30		0.001130	
	Tin	7440-31-5	0.25		0.000942	
	Zinc	7440-66-6	0.20		0.000754	
Leadframe Plating					0.001560	0.01%
	Silver	7440-22-4	100.00		0.001560	
Heat Sink					7.08725	64.76%
	Copper	7440-50-8	100.00		7.08725	
Ext. Heat Sink Plating					0.00547	0.05%
	Nickel	7440-02-0	100.00		0.005471	
Bond Wire					0.01153	0.11%
	Gold	7440-57-5	99.05		0.01142	
	Palladium	7440-05-3	0.9500		0.00011	
Ext. Plating					0.03346	0.31%
	Tin	7440-31-5	85.00		0.028441	
	Lead	7439-92-1	15.00		0.005019	

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Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
3/08/06	1.0	Initial release.
7/05/06	1.1	100% Material Declaration.
10/3/06	1.2	Updated component descriptions.